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(\$4) Title: CONDUCTIVE MOLDING COMPOSITIONS AND ARTICLES MOLDED THEREFROM (\$67) Abstract Electrically conductive, thermoset molding compositions are disclosed which comprise an unsaturated thermosetting resin, an elefinically unsaturated monomer which is copolymerizable with the thermosetting resin, a thermoplastic additive and carbon black. The darbon black is incorporated in a conductive additive which comprises the thermoplastic additive, the carbon black and, preferably, a lubricant. The electrical resistance of articles molded from the disclosed molding compositions is typically less than about 10 ⁸ ohms/cm².		